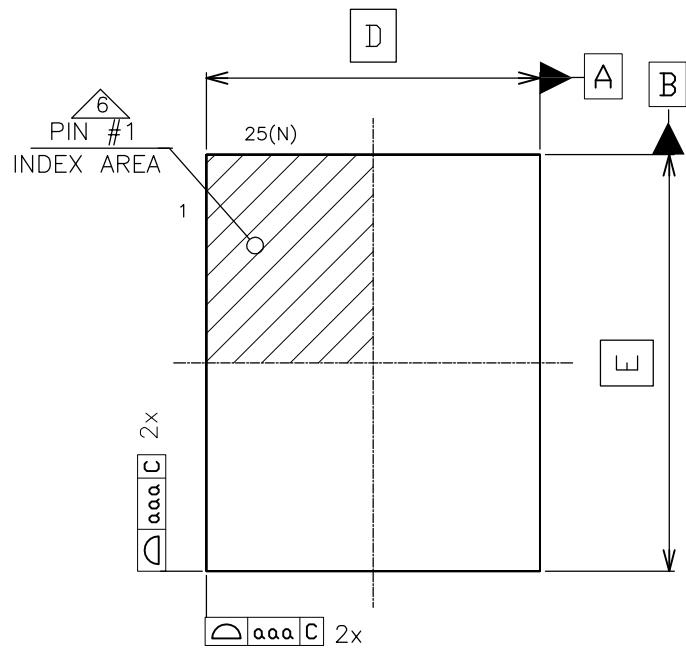
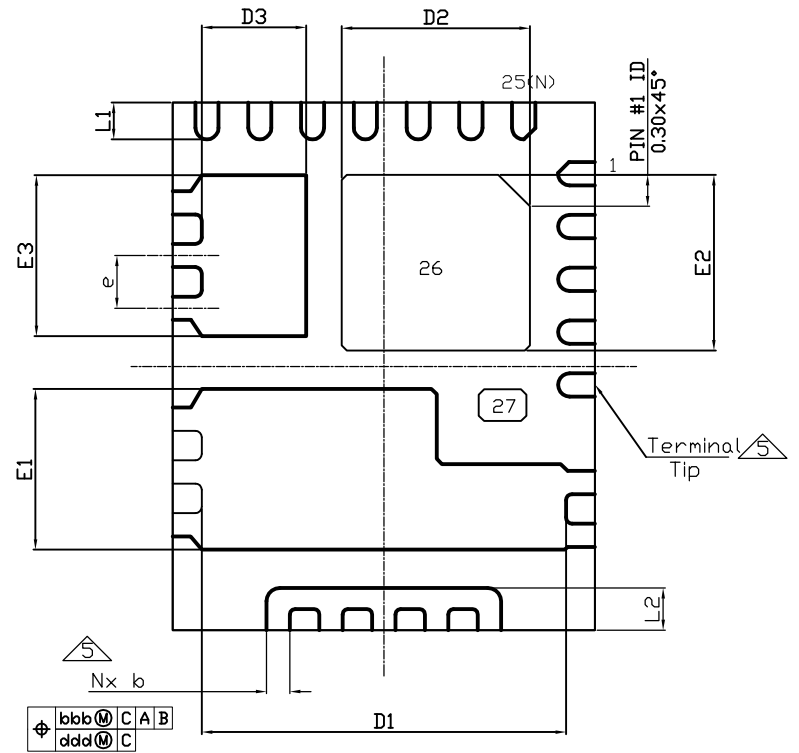


Revision History

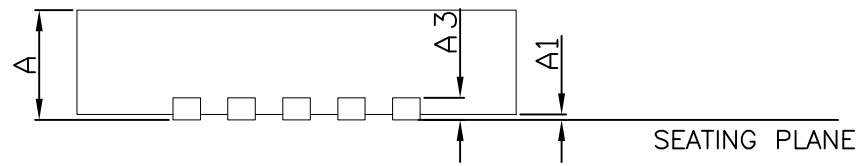
REV.	Description	Date	APP'D
B	27LD 5x4x1.0mm QFN Cu clip	FEB/15/2017	ECN 1717-33 04/28/2017jh



TOP VIEW



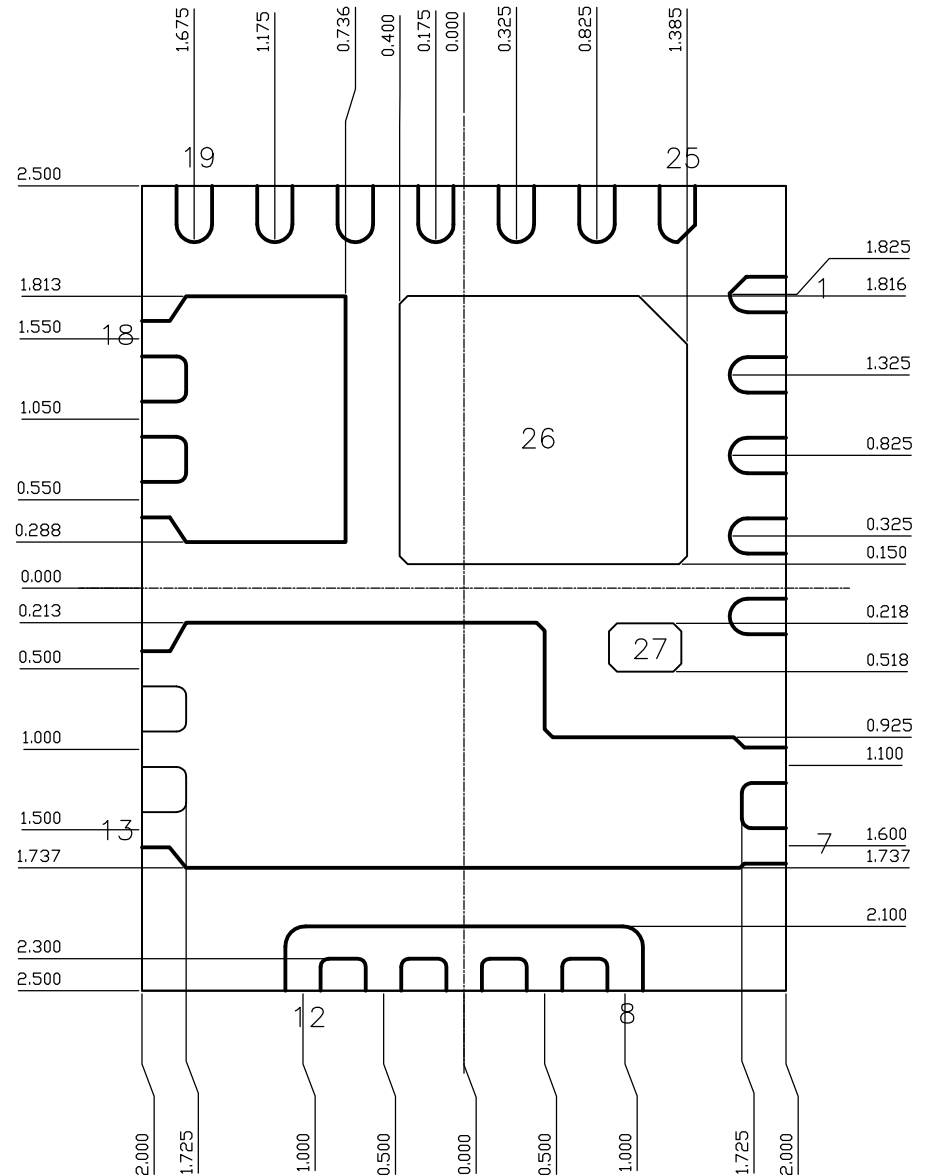
BOTTOM VIEW



SIDE VIEW

Dimension Table				
Thickness Symbol	V			NOTE
	MIN	NOM	MAX	
A	0.80	0.90	1.00	
A1	0.00	0.02	0.05	
A3	---	0.20Ref	---	
b	0.20	0.25	0.30	
D	4.00 BSC			
E	5.00 BSC			
e	0.50 BSC			
D1	3.350	3.450	3.550	
E1	1.424	1.524	1.624	
D2	1.685	1.785	1.885	
E2	1.566	1.666	1.766	
D3	0.889	0.989	1.089	
E3	1.425	1.525	1.625	
L1	0.25	0.35	0.45	
L2	0.30	0.40	0.50	
aaa	0.15			
bbb	0.10			
ccc	0.10			
ddd	0.05			
eee	0.08			
N	25			

TERMINAL DETAILS

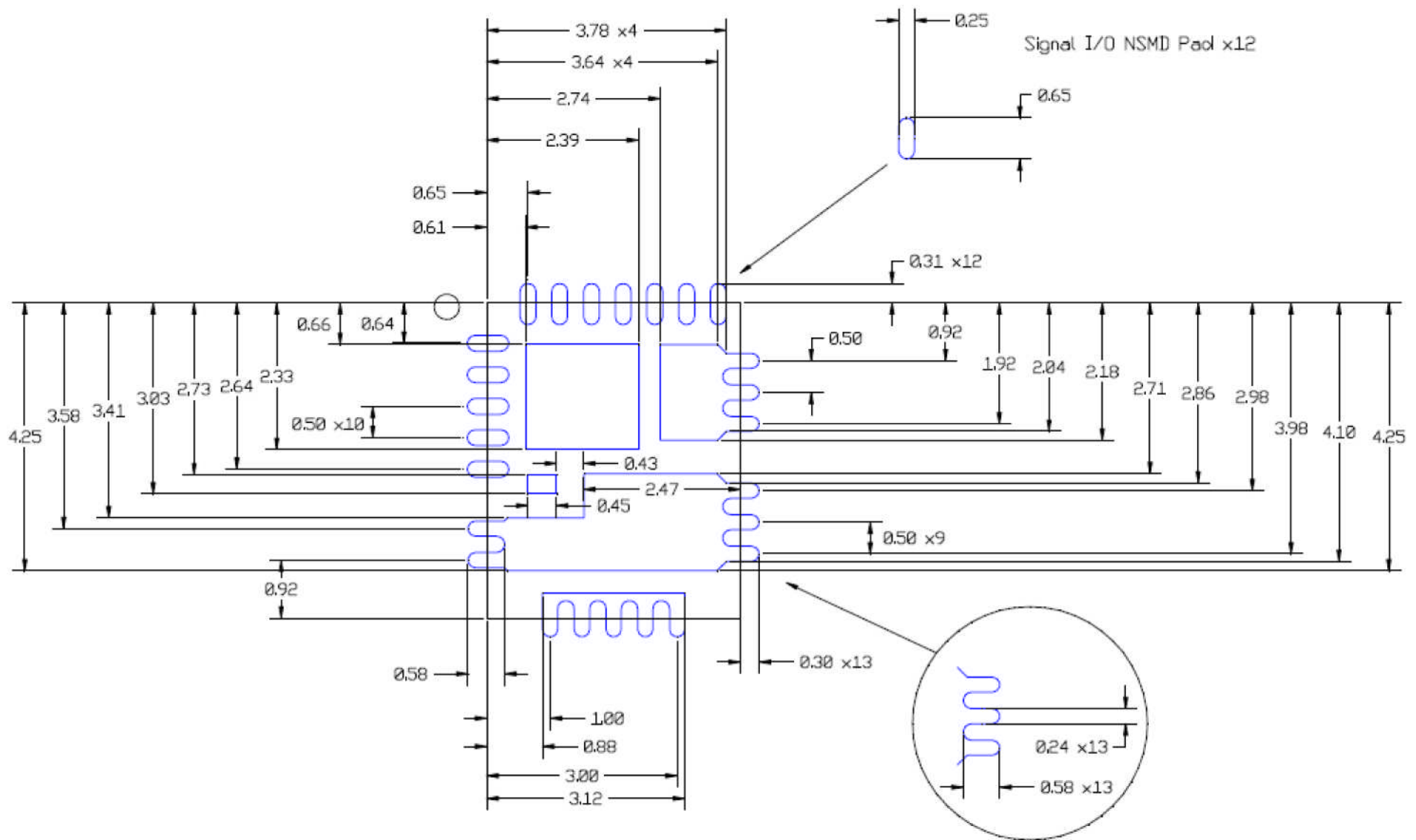


ALL DIMENSIONS ARE IN MILLIMETERS, ANGLES AREA IN DEGREE

		EXAR CORPORATION	
		27LD 5x4x1.0mm QFN Cu Clip Package Outline Drawing	
Packaging Approval:		Drawing No.: POD-0000085	
By: YG Eom	Date: FEB.15.2017	Revision: B	Sheet 1 OF 3

Revision History

REV.	Description	Date	APP'D
B	27LD 5x4x1.0mm QFN Cu clip	FEB/15/2017	ECN 1717-33 04/28/2017jh



Metal and component placement

PCB COPPER

NOTE 1 : LEAD LAND WIDTH SHOULD BE EQUAL TO NOMINAL PART LEAD WIDTH.

NOTE 2 : MINIMUM LEAD SPACE TO SPACE SHOULD BE $\geq 0.2\text{mm}$ TO PREVENT SHORTING.

NOTE 3 : LEAD LAND LENGTH SHOULD BE EQUAL TO MAXIMUM PART LEAD LENGTH $+0.15 -0.3\text{mm}$ OUTBOARD EXTENSION AND 0 TO $+0.05\text{mm}$ INBOARD EXTENSION.

THE OUTBOARD EXTENSION ENSURES A LARGE AND VISIBLE TOE FILLET AND THE INBOARD EXTENSION WILL ACCOMODATE ANY PART MISALIGNMENT AND ENSURE A FILLET.

NOTE 4 : CENTER PAD LAND LENGTH AND WIDTH SHOULD BE EQUAL TO MAXIMUM PART PAD LENGTH AND WIDTH. BUT, MIN 0.2mm SPACE AMONG PADS SHOULD BE KEPT TO PREVENT SHORTING.

NOTE 5 : ONLY $0.15-0.3\text{mm}$ DIAMETER VIA SHALL BE PLACED IN THE AREA OF THE POWER PAD LANDS AND CONNECTED TO POWER PLANES TO MINIMIZE THE NOISE EFFECT ON THE IC AND TO IMPROVE THERMAL PERFORMANCE.



EXAR CORPORATION

27LD 5x4x1.0mm QFN Cu Clip Package Outline Drawing

Packaging Approval:

Drawing No.: POD-00000085

By: YG Eom

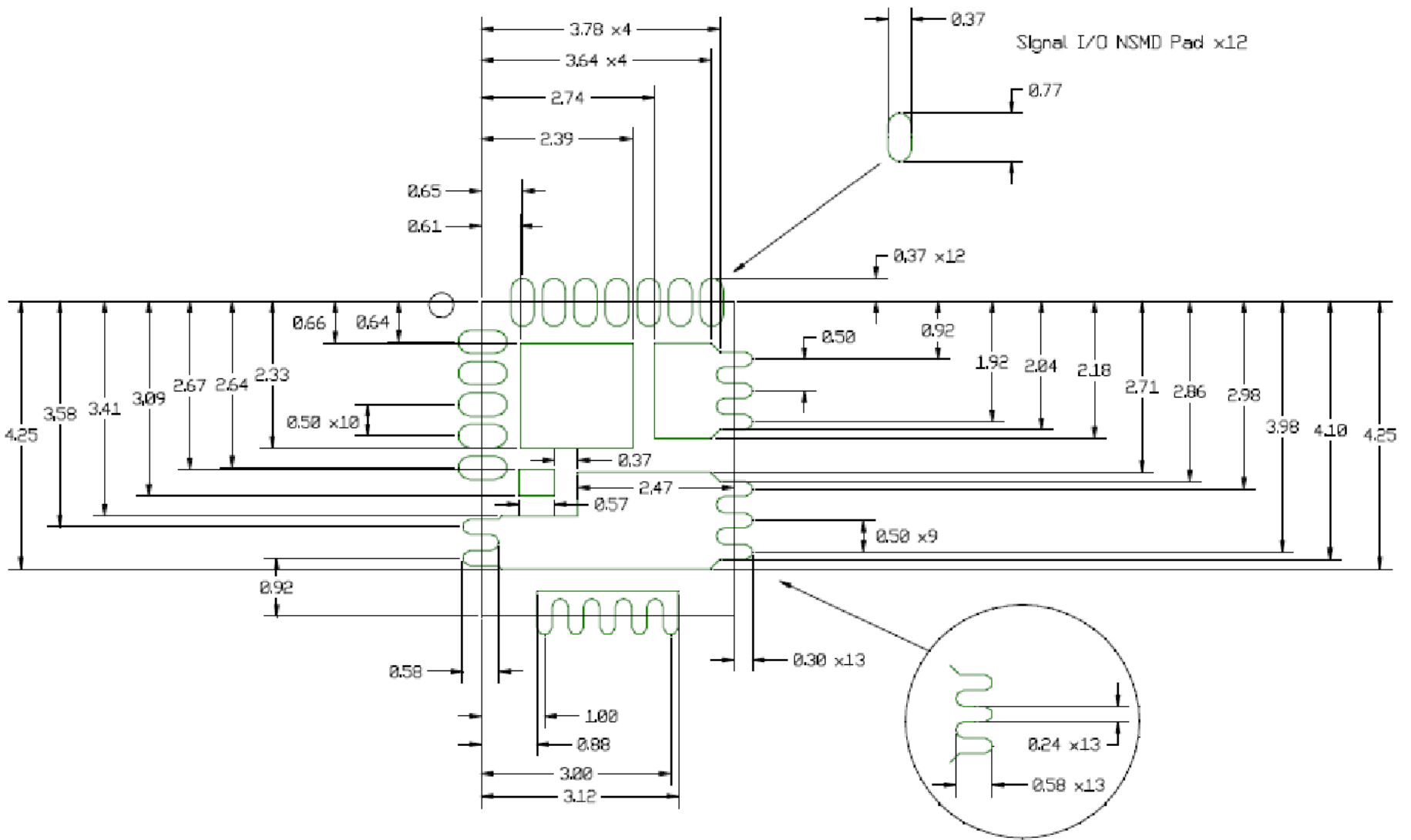
Date: FEB.15.2017

Revision: B

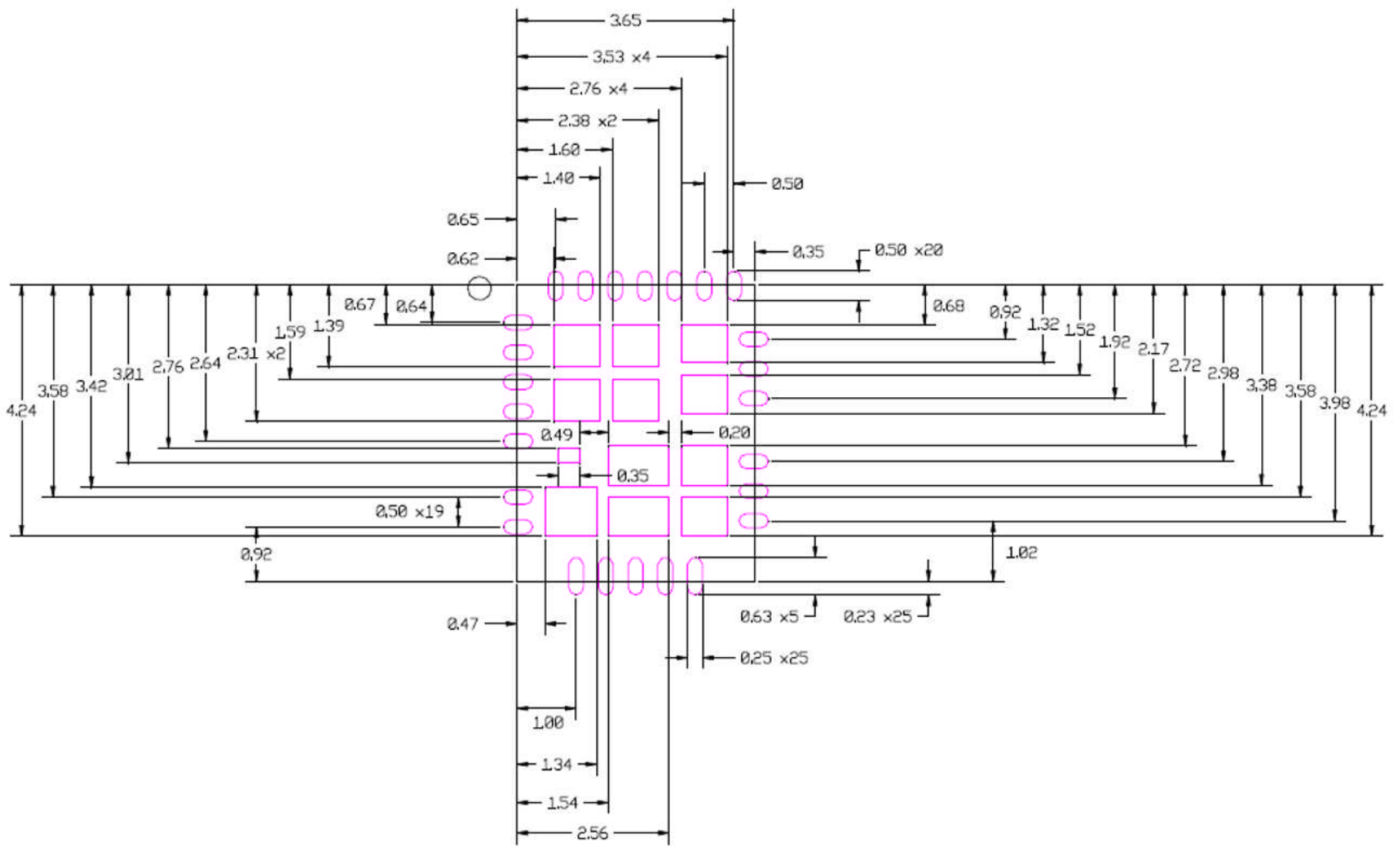
Sheet 2 OF 3

Revision History


REV.	Description	Date	APP'D
B	27LD 5x4x1.0mm QFN Cu clip	FEB/15/2017	ECN 1717-33 04/28/2017jh



PCB SOLDER MASK



TYPICAL RECOMMENDED STENCIL DESIGN

		EXAR CORPORATION	
		27LD 5x4x1.0mm QFN Cu Clip Package Outline Drawing	
Packaging Approval:		Drawing No.: POD-0000085	
By: YG Eom	Date: FEB.15.2017	Revision: B	Sheet 3 OF 3